

1310/1490 Integrated Diplexer Transceiver

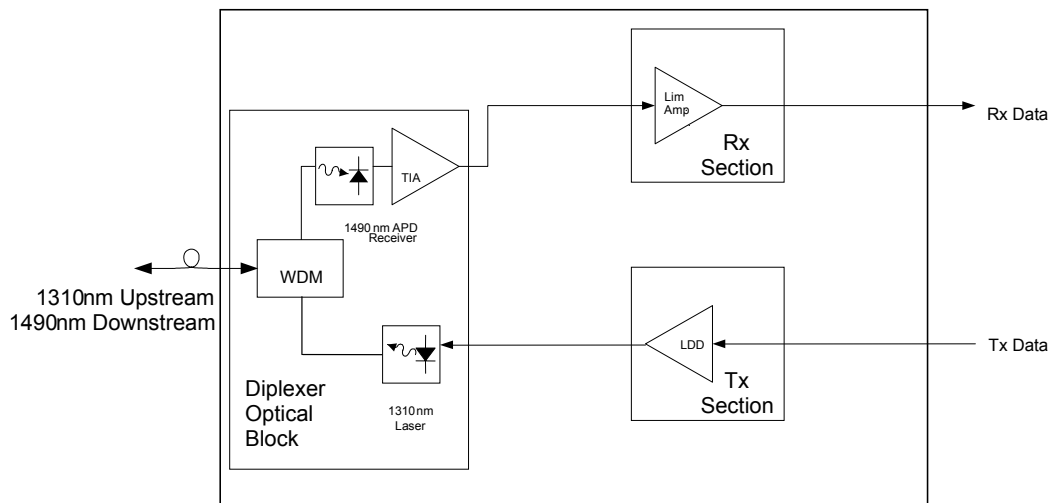


Features

- Simplex SC Connector, Integrated Diplexer Transceiver
- SFP MSA, digital diagnostics SFF-8472 Compliant
- Voice/Data FTTx ONT/ONU Applications
- Compliant to FSAN G.984.5 Specifications
- 1244 Mbps Tx, 2488 Mbps Rx Asymmetric Data Rate
- Burst Mode Transmission
- TX Burst Mode Detection, TX_SD
- RX Squelch
- Operating case temperature: -40~85°C
- 28 dB link budget; Class B+; 20km reach
- Compliant to IEC-60825 Class 1 laser diode
- RoHS Compliant
- Internal Calibration

- **Digital Transmitter:** A DFB laser diode is employed for upstream transmission at OC-24 (1244Mbps). The optical transmitter includes a back facet photodetector to monitor laser power for APC loop control.

- **Digital Receiver:** An APD with TIA is employed for downstream data reception at OC-48 (2488Mbps). A post amplifier is also included for CML output compatibility.



Diplexer Block Diagram

Absolute Maximum Ratings

Usage of this transceiver shall adhere to the following absolute maximum ratings. Stresses beyond those in Table 1 may cause permanent damage to the unit. These are stress ratings only, and functional operation of the unit at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect unit reliability.

Table 1 - Absolute Maximum Ratings

Parameter	Minimum	Maximum	Unit/Conditions
Ambient Storage Temperature	-40	85	°C
Operating Temperature*	-40	85	°C
Operating Humidity Range	5%	95%	non-condensing
ESD Sensitivity (Human Body Model)	-	1000	V
Lead Soldering Temperature	-	260°C	Maximum 10 sec
Vcc_Rx	-0.4	+4.2	V
Vcc_Tx	-0.4	Vcc_Rx + 1	V

Module Characteristics

Table 2 - Module Characteristics

Parameter	Minimum	Typical	Maximum	Unit/Conditions
1310nm Tx to 1490nm Rx Crosstalk	-	-	-47	dB
1555nm Rx to 1490nm Isolation	30	-	-	dB
G.984.5 Wavelength Blocking Filter (WBF)	7	-	-	dB, 1441 nm to 1450 nm
	7	-	-	dB, 1530 nm to 1539 nm
	22	-	-	dB, 1400 nm to 1441 nm
	22	-	-	dB, 1539 nm to 1625 nm
Total TX and RX Supply Current	-	-	350	mA

Functional Characteristics

The following tables list the performance specifications for the various functional blocks of the integrated optical transceiver module.

Table 3 – Digital Transmitter Specifications

Parameter	Minimum	Typical	Maximum	Unit	Notes
Operating Voltage	3.14	3.30	3.46	V	V _{CC} referenced to GND_Tx
Data Rate	-	1244.16	-	Mbps	
Average Optical Output Power, P _O	0.5	-	5	dBm	
Output Power at Transmit Off	-	-	-45	dBm	
Extinction Ratio	10	-	-	dB	PRBS 2 ²³ -1, NRZ, 50% duty cycle
Transmitter Output Eye	G.984.2 Figure 3				
Optical Rise and Fall Time	-	250	-	ps	20% to 80%
Side Mode Suppression Ration (SMSR)	30			dB	
Center Wavelength	1290		1330	nm	
-20dB Spectral Width			1	nm	
Differential Input Voltage	300	-	1800	mVp-p	TXD+/-, Internally DC-coupled
Input Impedance	-	100	-	Ω	CML input/R3=100ohm
Common-Mode Input Voltage	GND_Tx + 1.4	-	V _{CC} - (V _{in} /2) - 0.1	V	Internally DC coupled
Tx Burst Enable Time	-	-	12.86	ns	16 bits data @ 1244Mbps
Tx Burst Disable Time	-	-	12.86	ns	16 bits data @ 1244Mbps
Jitter Generation	-	-	0.2	UI	4 kHz to 10 MHz

Refer to Figure 1 which schematically describes the timing parameter definition in burst mode sequence.

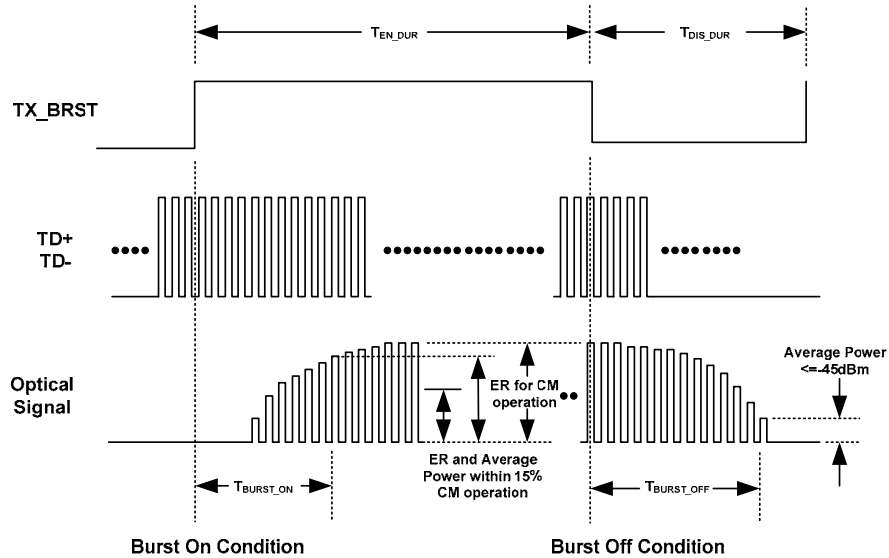


Figure 1 - Timing Parameter Definition in Burst Mode Sequence

Table 4 – Digital Receiver Specifications

Parameter	Minimum	Typical	Maximum	Unit	Notes
Operating Voltage	3.14	3.30	3.46	V	V_{CC} referenced to GND_RX
Data Rate	-	2488.32	-	Mbps	
Operational Wavelength Range	1480	-	1500	nm	
Received Optical Power (BOL)	-28	-	-8	dBm	BER $\leq 10^{-10}$, PRBS 2 ²³ -1, 50% duty cycle
Received Optical Power (EOL)	-27	-	-8	dBm	
Data Output Rise and Fall Time	-	160	-	ps	20% to 80%
Signal Detect Assert Level	-	-	-29	dBm	Transition during increasing light
Signal Detect De-assert Level	-45	-	-	dBm	Transition during decreasing light
Hysteresis	0.5	-	-	dB	
Differential Output Voltage	300	-	1200	mV	CML output, ac coupled
Signal Detect Output HIGH Voltage	2.4	-	-	V	LVTTL with internal pull up resistor. Asserts HIGH when input data amplitude is above threshold.
Signal Detect Output LOW Voltage	-	-	0.6	V	LVTTL with internal pull up resistor. De-asserts LOW when input data amplitude is below threshold.

Table 5 - Microcontroller Specifications

Parameter	Minimum	Typical	Maximum	Unit	Notes
Operating Voltage	3.14	3.30	3.46	V	
SDA ^a	-	-	-	-	LVTTTL, open collector serial data line from the I ² C bus to the on board Microcontroller.
SCL ^b	-	-	-	-	LVTTTL, open collector serial clock line from the I ² C bus to the on board Microcontroller. 400kbps max. data rate.

^a I²C SDA and SCL must be open collector or open drain connections.

^b Clock stretching, as per paragraph 13.2 of the I²C Bus Standard, must be implemented to operate correctly.

Recommended Interface Circuit

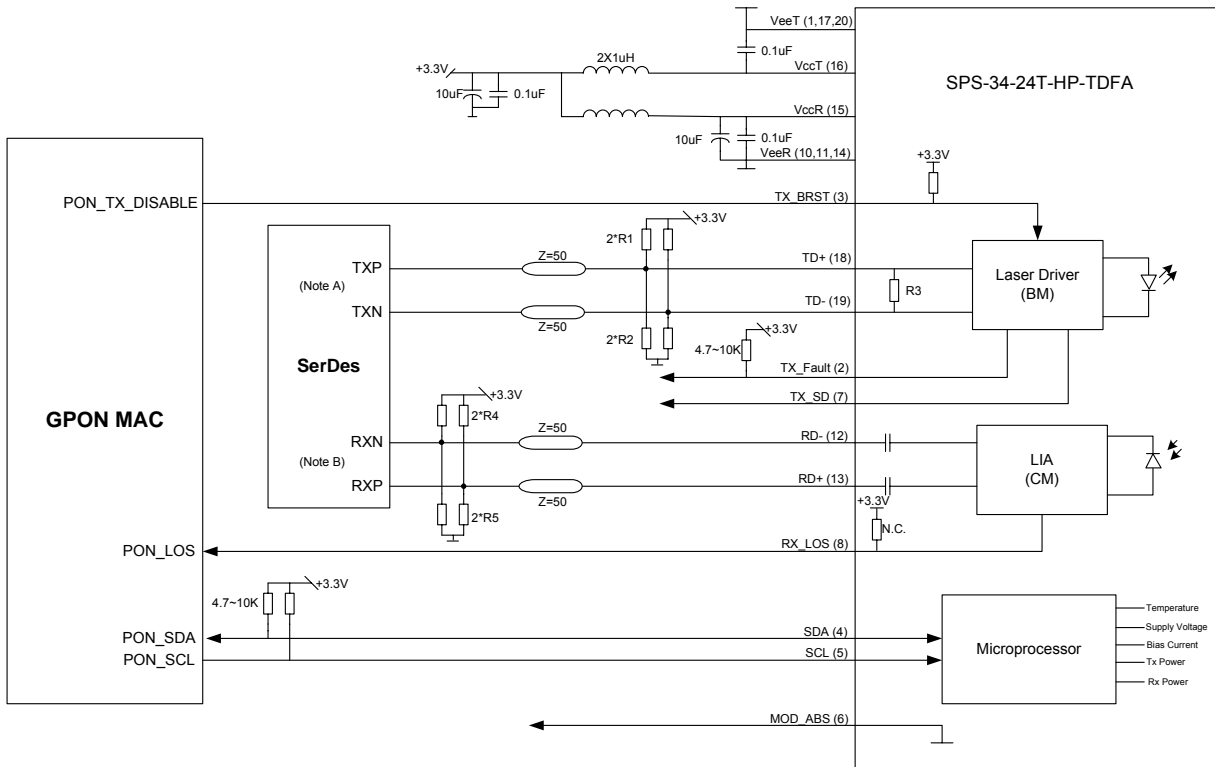


Figure 2 – Recommended interface circuit

Note A: Output stage in SerDes IC is LVPECL output, R1=130ohm, R2=82ohm, R3=N.C.

Output stage in SerDes IC is CML output, R1=N.C., R3=100ohm.

Note B: CML output, AC coupled internally.

Input stage in SerDes IC is LVPECL input, R4=82ohm, R5=130ohm

Input stage in SerDes IC is CML input, R4=R5=N.C.

Pin Definitions

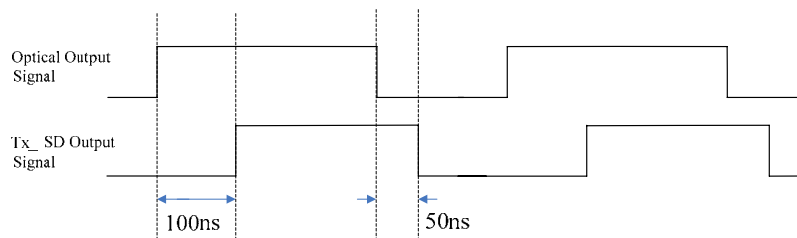
Refer to [错误! 未找到引用源。6](#) for a description of the function of each I/O pin.

Table 6 - Module Pin Definitions

Pin Number	Label	Definition	Note
1	VeeT	Module Transmitter Ground	
2	TX_FAULT	Module Transmitter Fault	
3	TX_BRST	Transmitter Burst Control, Active High	
4	SDA	2-Wire Serial Interface Data Line (MOD-DEF2)	1
5	SCL	2-Wire Serial Interface Clock (MOD-DEF1)	1
6	MOD_ABS	Module Absent, connected to VeeT or VeeR in the module	
7	TX_SD	TX Signal Detect	2
8	RX_SD	Receiver Signal Detect	
9	NC	Not connected	
10	VeeR	Module Receiver Ground	
11	VeeR	Module Receiver Ground	
12	RXD-	Receiver Inverted Data Output	
13	RXD+	Receiver Non-Inverted Data Output	
14	VeeR	Module Receiver Ground	
15	VCCR	Module Receiver 3.3V Supply	
16	VCCT	Module Transmitter 3.3V Supply	
17	VeeT	Module Transmitter Ground	
18	TXD+	Transmitter Non-Inverted Data Input, CML with 100ohm differential impedance	
19	TXD-	Transmitter Inverted Data Input, CML with 100ohm differential impedance	
20	VeeT	Module Transmitter Ground	

Note

1. This pin is an open collector/drain output pin and shall be pulled up with 4.7K-10K ohms to a Host_Vcc on the host board.
2. TX Signal Detect, TX Active State: High.



Pin Assignment

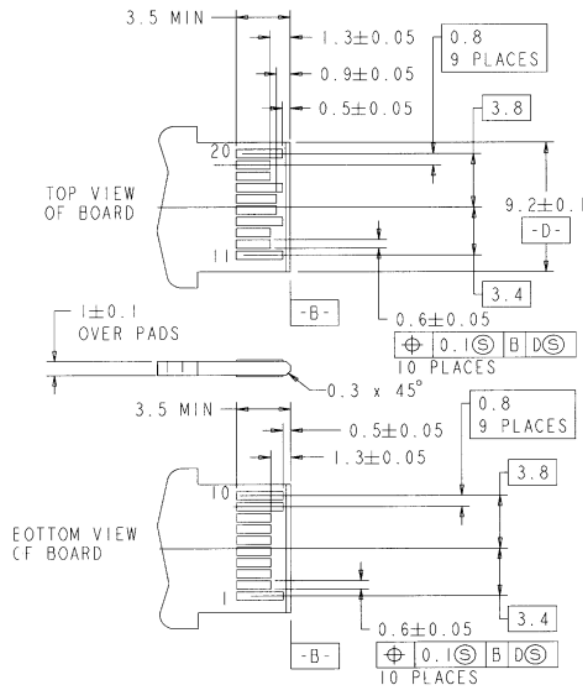


Figure 3, SFP Pin View (Golden Finger)

Recommended Host Board Power Supply Circuit

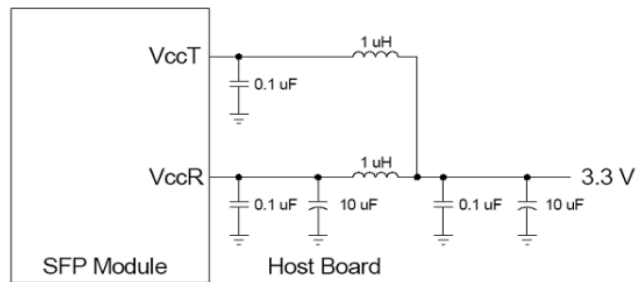


Figure 4, Recommended Host Board Power Supply Filtering Network

Digital Diagnostics Monitor Accuracy

Table 7 - Diagnostics

Parameter	Range	Accuracy	Unit	Calibration
Temperature	-40 to 100	±3	°C	Internal
Voltage	0 to Vcc	±3%	V	Internal
Bias Current	0 to 100	±10%	mA	Internal
Tx Power	-1 to 5	±2	dB	Internal
Rx Power	-28 to -8	±3	dB	Internal

Note

1. Temperature and voltage are measured internal to the transceiver.
2. Bias monitor is specified by nominal bias value at continuous mode.

EEPROM information

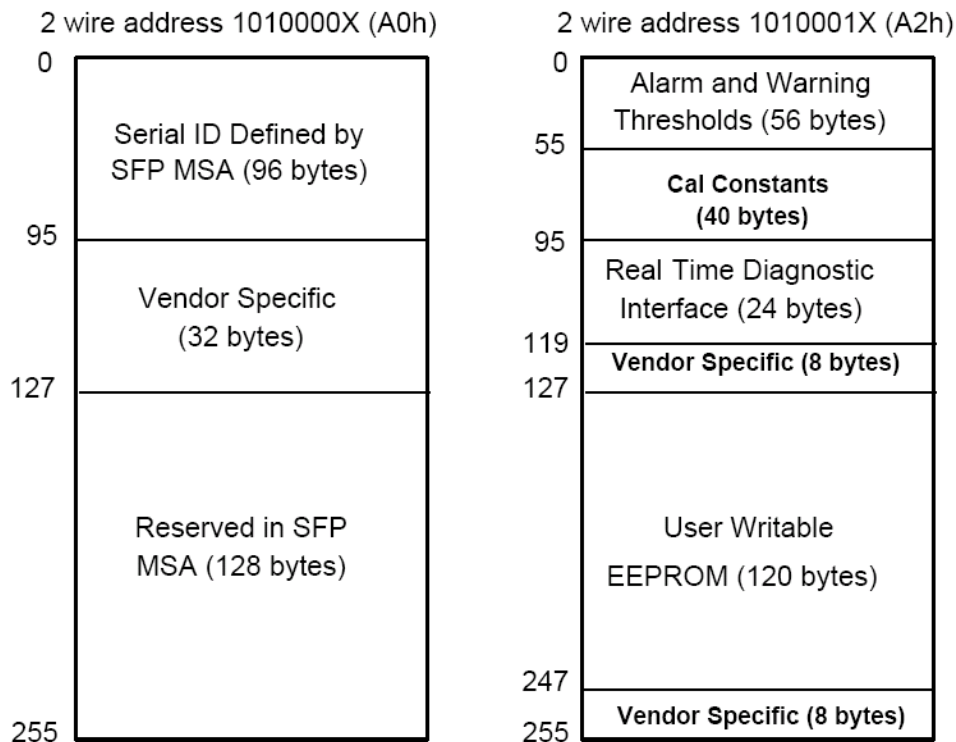


Figure 5, 2-wire Serial Digital Diagnostic Memory Map

Table 8 - EEPROM Serial ID Memory Contents (A0h)

Addr.	Field Size (Bytes)	Name of Field	Hex	Description
0	1	Identifier	03	SFP transceiver
1	1	Ext. Identifier	04	MOD4
2	1	Connector	01	SC
3-10	8	Transceiver	00 00 00 00 00 00 00 00	
11	1	Encoding	03	NRZ
12	1	BR, Nominal	0C	1.244Gbps
13	1	Reserved	00	
14	1	Length (9um)-km	14	20(km)
15	1	Length (9um)	C8	200(100m)
16	1	Length (50um)	00	Not Support MMF
17	1	Length (62.5um)	00	Not Support MMF
18	1	Length (Copper)	00	Not Support Copper
19	1	Reserved	00	
20-35	16	Vendor name	53 4F 55 52 43 45 50 48 4F 54 4F 4E 49 43 53 20	"SOURCEPHOTONICS"(ASC II)
36	1	Reserved	00	
37-39	3	Vendor OUI	00 00 00	
40-55	16	Vendor PN	53 50 53 33 34 32 34 54 48 50 54 44 46 41 20 20	"SPS3424THPTDFA" (ASCII)
56-59	4	Vendor Rev	xx xx 20 20	ASCII("31 30 20 20" means 1.0 Revision)
60-61	2	Wavelength	05 1E	1310nm Laser Wavelength
62	1	Reserved	00	
63	1	CC_BASE	xx	Check sum of byte 0-62
64-65	2	Options	00 0C	Rx_SD, Tx_Fault
66	1	BR, max	00	
67	1	BR, min	00	
68-83	16	Vendor SN	xx xx xx xx xx xx xx xx xx xx xx xx xx xx xx xx	ASCII
84-91	8	Date code	xx xx xx xx xx xx 20 20	Year(2 bytes),Month(2 bytes), Day(2 bytes)
92	1	Diagnostic Monitoring Type	68	Compliant with SFF-8472 V9.5 Internally Calibrated Received power measurement type -Average Power
93	1	Enhanced Options	F0	Diagnostics (Optional Alarm/warning flags) Soft TX_FAULT monitoring implemented

				Soft RX_LOS monitoring implemented
94	1	SFF-8472 Compliance	02	Diagnostics Compliance(SFF-8472 V9.5)
95	1	CC_EXT	xx	Check sum of byte 64-94
96-255	64	Vendor Specific		

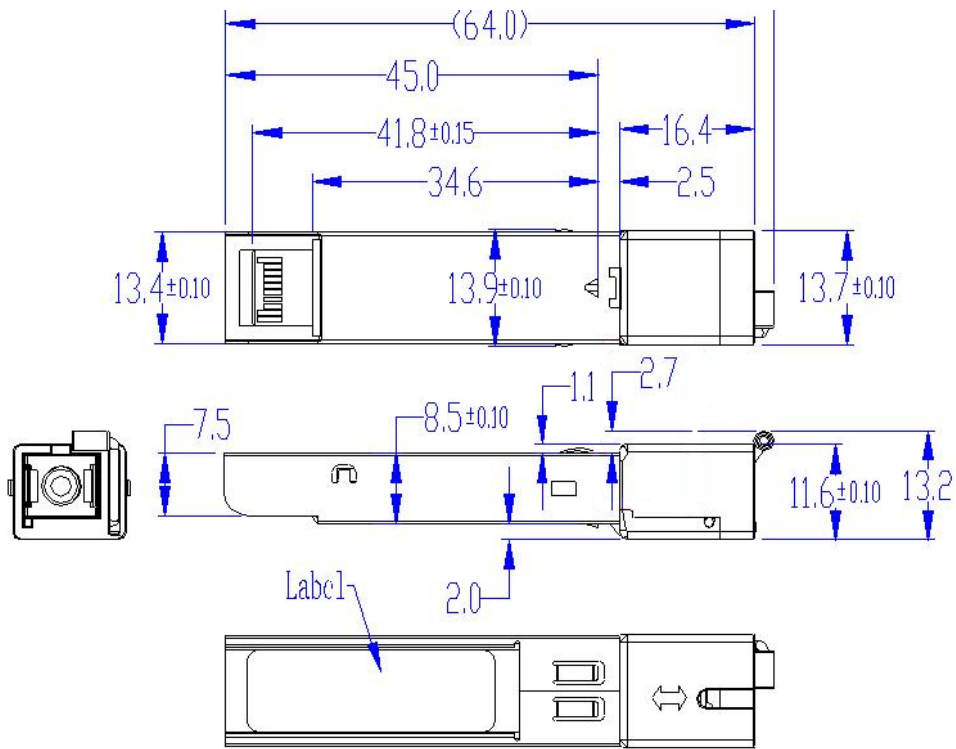
Table 9 - EEPROM Serial ID Memory Contents (A2h)

Addr.	Field Size (Bytes)	Name of Field	Hex	Description
0	00	Temp High Alarm	64 00	100 °C
2	02	Temp Low Alarm	CE 00	-50 °C
4	04	Temp High Warning	5A 00	90 °C
6	06	Temp Low Warning	D8 00	-40 °C
8	08	Voltage High Alarm	8C A0	3.6V
10	0A	Voltage Low Alarm	75 30	3.0V
12	0C	Voltage High Warning	88 B8	3.5V
14	0E	Voltage Low Warning	79 18	3.1V
16	10	Bias High Alarm	AF C8	90mA
18	12	Bias Low Alarm	00 00	0mA
20	14	Bias High Warning	88 B8	70mA
22	16	Bias Low Warning	00 00	0mA
24	18	TX Power High Alarm	7B 86	5dBm
26	1A	TX Power Low Alarm	22 D0	-0.5dBm
28	1C	TX Power High Warning	6E 17	4.5dBm
30	1E	TX Power Low Warning	27 10	0dBm
32	20	RX Power High Alarm	07 CB	-7dBm
34	22	RX Power Low Alarm	00 0F	-28dBm
36	24	RX Power High Warning	06 30	-8dBm
38	26	RX Power Low Warning	00 14	-27dBm
40	28	Reserved	00...000	Reserved
56	38	RX_PWR(4) Calibration	00 00 00 00	4th order RSSI calibration coefficient
60	3C	RX_PWR(3) Calibration	00 00 00 00	3rd order RSSI calibration coefficient
64	40	RX_PWR(2) Calibration	00 00 00 00	2nd order RSSI calibration coefficient
68	44	RX_PWR(1) Calibration	3F 80 00 00	1st order RSSI calibration coefficient
72	48	RX_PWR(0) Calibration	00 00 00 00	0th order RSSI calibration coefficient
76	4C	TX_I(Slope) Calibration	01 00	Slope for Bias calibration
78	4E	TX_I(Offset) Calibration	00 00	Offset for Bias calibration
80	50	TX_PWR(Slope) Calibration	01 00	Slope for TX Power calibration

82	52	2	TX_PWR(Offset) Calibration	00 00	Offset for TX Power calibration
84	54	2	T(Slope) Calibration	01 00	Slope for Temperature calibration
86	56	2	T(Offset) Calibration	00 00	Offset for Temperature calibration, in units of 256ths C
88	58	2	V(Slope) Calibration	01 00	Slope for VCC calibration
90	5A	2	V(Offset) Calibration	00 00	Offset for VCC calibration
92	5C	3	Reserved	00 00 00	Reserved
95	5F	1	Checksum	xx	Checksum
96	60	2	Transceiver Temperature	xx xx	Temperature in C/256
98	62	2	Supply Voltage	xx xx	Vcc
100	64	2	TX Bias Current	xx xx	BIASMON
102	66	2	TX Optical Output Power	xx xx	Back facet monitor
104	68	2	RX Optical Input Power	xx xx	RSSI
106	6A	2	Reserved	00 00	Reserved
108	6C	2	Reserved	00 00	Reserved
110	6E.7	1bit	TX_DIS State	x	Soft TX disable state
	6E.6	1bit	Soft TX Disable	x	Write bit that allows software disable laser output.
	6E.5	1bit	Reserved.	0	Reserved
	6E.4	1bit	Rate Select State	0	NOT SUPPORTED.
	6E.3	1bit	Rate Select	0	NOT SUPPORTED.
	6E.2	1bit	TX_FAULT	x	Digital state of the TX Fault Output
	6E.1	1bit	Rx LOS	x	Digital state of the Rx LOS Output
	6E.0	1bit	Data Ready Bar	x	Indicates transceiver has achieved power up and data is ready.
111	6F.7	1bit	Reserved	0	Reserved
	6F.6	1bit	Reserved	0	Reserved
	6F.5	1bit	Reserved	0	Reserved
	6F.4	1bit	Reserved	0	Reserved
	6F.3	1bit	Reserved	0	Reserved
	6F.2	1bit	Reserved	x	Reserved
	6F.1	1bit	Reserved	0	Reserved
	6F.0	1bit	Reserved	x	Reserved
112	70.7	1bit	Temperature too high alarm	x	Temperature too high alarm
	70.6	1bit	Temperature too low alarm	x	Temperature too low alarm
	70.5	1bit	VCC too high alarm	x	VCC too high alarm
	70.4	1bit	VCC too low alarm	x	VCC too low alarm
	70.3	1bit	BIASMON too high alarm	x	BIASMON too high alarm

	70.2	1bit	BIASMON too low alarm	x	BIASMON too low alarm
	70.1	1bit	TX Power too high alarm	x	TX Power too high alarm
	70.0	1bit	TX Power too low alarm	x	TX Power too low alarm
113	71.7	1bit	RX Power too high alarm	x	RX Power too high alarm
	71.6	1bit	RX Power too low alarm	x	RX Power too low alarm
	71.5	1bit	Reserved interrupt status bit	x	Reserved interrupt status bit
	71.4	1bit	Reserved interrupt status bit	x	Reserved interrupt status bit
	71.3	1bit	Reserved interrupt status bit	x	Reserved interrupt status bit
	71.2	1bit	Reserved interrupt status bit	x	Reserved interrupt status bit
	71.1	1bit	Reserved interrupt status bit	x	Reserved interrupt status bit
	71.0	1bit	Reserved interrupt status bit	x	Reserved interrupt status bit
114	72	1	Reserved	00	Reserved
115	73	1	Reserved	00	Reserved
116	74.7	1bit	Temperature too high warning	x	Temperature too high warning
	74.6	1bit	Temperature too low warning	x	Temperature too low warning
	74.5	1bit	VCC too high warning	x	VCC too high warning
	74.4	1bit	VCC too low warning	x	VCC too low warning
	74.3	1bit	BIASMON too high warning	x	BIASMON too high warning
	74.2	1bit	BIASMON too low warning	x	BIASMON too low warning
	74.1	1bit	TX Power too high warning	x	TX Power too high warning
	74.0	1bit	TX Power too low warning	x	TX Power too low warning
117	75.7	1bit	RX Power too high warning	x	RX Power too high warning
	75.6	1bit	RX Power too low warning	x	RX Power too low warning
	75.5	1bit	Reserved interrupt status bit	0	Reserved interrupt status bit
	75.4	1bit	Reserved interrupt status bit	0	Reserved interrupt status bit
	75.3	1bit	Reserved interrupt status bit	0	Reserved interrupt status bit
	75.2	1bit	Reserved interrupt status bit	0	Reserved interrupt status bit
	75.1	1bit	Reserved interrupt status bit	0	Reserved interrupt status bit
	75.0	1bit	Reserved interrupt status bit	0	Reserved interrupt status bit
118	76	1	Reserved	00	Reserved
119	77	1	Reserved	00	Reserved
120	78	8	Vendor Specific	00 00 00 00 00 00 00 00	Vendor Specific

Mechanical Diagram



Ordering Information

Table 10 – Valid Part Numbers

Part Number	Description
SPS-34-24T-HP-TDFA	GPON ONT diplexer optical transceiver, SFP, Industrial temperature range operation

Table 11 - Device Handling/ESD Protection

The devices are static sensitive and may easily be damaged if care is not taken during handling. The following handling practices are recommended.

1	Devices should be handled on benches with conductive and grounding surfaces.
2	All personnel, test equipment and tools shall be grounded.
3	Do not handle the devices by their leads.
4	Store devices in protective foam or carriers.
5	Avoid the use of non-conductive plastics, rubber, or silk in the area where the devices are handled
6	All modules shall be packaged in materials that are anti-static to protect against adverse electrical environments.
7	Avoid applications of any voltage higher than maximum rated voltages to this part. For proper operation, any VIN or VOUT should be constrained to the range $GND \leq (VIN \text{ or } VOUT) \leq VCC$. Unused inputs must always be tied to an appropriate logic voltage (e.g. either GND or VCC). Unused outputs must be left open.

Warnings

Handling Precautions: This device is susceptible to damage as a result of electrostatic discharge (ESD). A static free environment is highly recommended. Follow guidelines according to proper ESD procedures.

Laser Safety: Radiation emitted by laser devices can be dangerous to human eyes. Avoid eye exposure to direct or indirect radiation.

Legal Notice

IMPORTANT NOTICE!

All information contained in this document is subject to change without notice, at Source Photonics' sole and absolute discretion. Source Photonics warrants performance of its products to current specifications only in accordance with the company's standard one-year warranty; however, specifications designated as "preliminary" are given to describe components only, and Source Photonics expressly disclaims any and all warranties for said products, including express, implied, and statutory warranties, warranties of merchantability, fitness for a particular purpose, and non-infringement of proprietary rights. Please refer to the company's Terms and Conditions of Sale for further warranty information.

Source Photonics assumes no liability for applications assistance, customer product design, software performance, or infringement of patents, services, or intellectual property described herein. No license, either express or implied, is granted under any patent right, copyright, or intellectual property right, and Source Photonics makes no representations or warranties that the product(s) described herein are free from patent, copyright, or intellectual property rights. Products described in this document are NOT intended for use in implantation or other life support applications where malfunction may result in injury or death to persons. Source Photonics customers using or selling products for use in such applications do so at their own risk and agree to fully defend and indemnify Source Photonics for any damages resulting from such use or sale.

© Copyright Source Photonics, Inc. 2007~2008

All Rights Reserved.

All information contained in this document is subject to change without notice. The products described in this document are NOT intended for use in implantation or other life support applications where malfunction may result in injury or death to persons.

The information contained in this document does not affect or change Source Photonics product specifications or warranties. Nothing in this document shall operate as an express or implied license or indemnity under the intellectual property rights of Source Photonics or third parties. All information contained in this document was obtained in specific environments, and is presented as an illustration. The results obtained in other operating environments may vary.

THE INFORMATION CONTAINED IN THIS DOCUMENT IS PROVIDED ON AN "AS IS" BASIS. In no event will Source Photonics be liable for damages arising directly from any use of the information contained in this document.

Contact

SOURCE PHOTONICS
20550 NORDHOFF ST.
CHATSWORTH, CA 91311

sales@sourcephotonics.com

Tel: 818-773-9044 Fax: 818-576-9486

Or visit our website: <http://www.sourcephotonics.com>